

BALL GRID ARRAY SOLDER ATTACHMENT

ABSTRACT

Reflow Grid Array (RGA) technology may be implemented on an interposer device, where the interposer is placed between a motherboard and a ball grid array (BGA) package. The interposer may provide a controlled heat source to reflow solder between the interposer and the BGA package. A technical problem faced by an interposer using RGA technology is application of solder to the RGA interposer. Technical solutions described herein provide processes and equipment for application of solder and formation of solder balls to connect an RGA interposer to a BGA package.

Fig. 2